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cont'd

26. A light emitting device according to claim 21, wherein at least one of the first conductive coating and the second conductive coating is formed by a printing method.

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39. A light emitting device according to claim 37, wherein the first, second, and third switching elements are p-channel thin film transistors.

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45. A light emitting device according to claim 37, wherein the conductor is made of the same material as a gate electrode of the first, second, and third switching element.

P
D
E
N
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T
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U
D
D
D

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46. A light emitting device according to claim 37, wherein at least one of the first, second, and third switching element comprises at least one thin film transistor.

50. A light emitting device according to claim 49, wherein the impurity region in at least one of the first, second, and third switching elements comprises a region having a concentration gradient at least at an impurity concentration of 1×10^{17} to $1 \times 10^{18} / \text{cm}^3$, and the impurity concentration is increased as a distance from the channel forming region increases.

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55. A light emitting device according to claim 52, wherein the first, second, and third switching elements are p-channel thin film transistors.

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61. A light emitting device according to claim 52, wherein the conductor is made of the same material as a gate electrode of the switching element.

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65. A light emitting device according to claim 64, wherein the impurity region in at least one of the first, second, and third switching elements comprises a region having a concentration gradient at least at an impurity concentration of 1×10^{17} to $1 \times 10^{18} / \text{cm}^3$, and the impurity concentration is increased as a distance from the channel forming region increases.

~~All~~ 69. A method of manufacturing a light emitting device according to claim 67, wherein forming the conductive coating further comprises connecting the conductor with a wiring to be the same potential.

70. A method of manufacturing a light emitting device according to claim 69, further comprising separating the wiring using a laser light after forming the conductive coating.

71. A method of manufacturing a light emitting device according to claim 69, further comprising separating the wiring simultaneously with the substrate after plating.

~~All~~ 74. A method of manufacturing a light emitting device according to claim 72, wherein forming the conductive coating further comprises connecting the conductor with a wiring to be the same potential.

75. A method of manufacturing a light emitting device according to claim 74, further comprising separating the wiring using a laser light after forming the conductive coating.

76. A method of manufacturing a light emitting device according to claim 74, further comprising separating the wiring simultaneously with the substrate after plating.